



# SOT552-1

plastic, thin shrink small outline package; 10 terminals; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

9 January 2017

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	3 x 3 x 1.1
<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP10
<b>Package outline version code</b>	SOT552-1
<b>Manufacturer package code</b>	SOT552
<b>Package type industry code</b>	TSSOP10
<b>Package outline version description</b>	plastic, thin shrink small outline package; 10 terminals; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P
<b>Handling precautions</b>	IC26_CHAPTER_3_2000
<b>Thermal design considerations</b>	IC26_CHAPTER_6_2000
<b>Mounting method type</b>	S (surface mount)
<b>Generic mounting and soldering information</b>	AN10365_3
<b>Reflow soldering footprint</b>	sot552-1_fr
<b>Wave soldering footprint</b>	sot552-1_fw
<b>Package life cycle status</b>	REL
<b>Major version date</b>	18-9-2008
<b>Minor version date</b>	11-5-2012
<b>Security status</b>	COMPANY PUBLIC
<b>Modified date</b>	11-5-2012
<b>Issue date</b>	18-2-2003
<b>Web publication date</b>	28-11-2012
<b>Initial web publication date</b>	18-1-2011
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product
<b>Package author</b>	Nair Deepa
<b>Package approver</b>	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A <sub>2</sub>	package height	0.8	-	0.9	0.95	mm
A	seated height	-	-	1.1	1.1	mm



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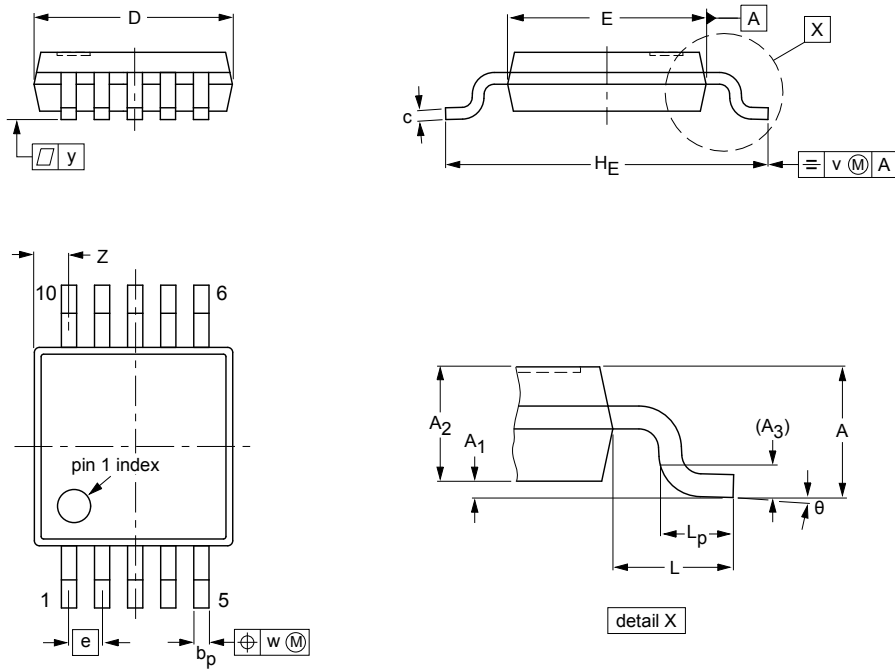
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		2.9	-	3	3.1	mm
e	nominal pitch		-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	10	-	

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## 2. Package outline

TSSOP10: plastic thin shrink small outline package; 10 leads; body width 3 mm

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**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.15	0.23 0.15	3.1 2.9	3.1 2.9	0.5	5.0 4.8	0.95	0.7 0.4	0.1	0.1	0.1	0.67 0.34	6° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT552-1						99-07-29 03-02-18

Fig. 1. Package outline TSSOP10 (SOT552-1)

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### 3. Soldering

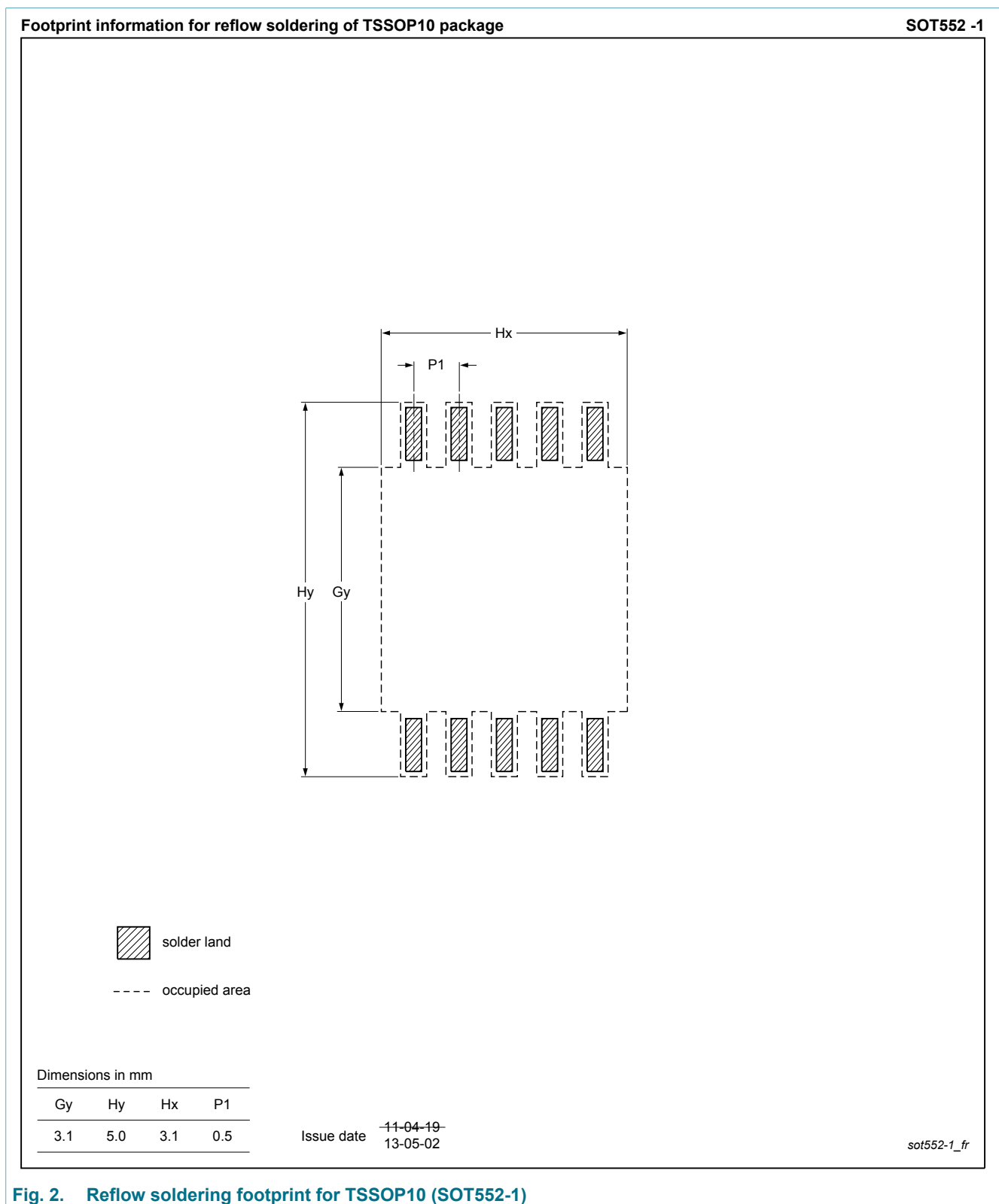


Fig. 2. Reflow soldering footprint for TSSOP10 (SOT552-1)

plastic, thin shrink small outline package; 10 terminals; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

## 4. Legal information

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